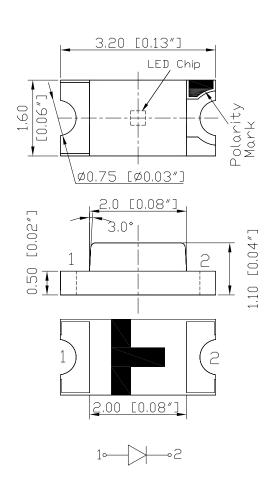
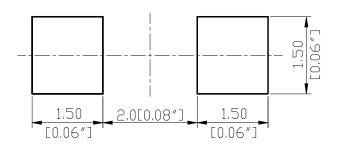


SPECIFICATION CS126AGT2C-R

PACKAGE OUTLINES



RECOMMEND PAD LAYOUT



ITEM	MATERIALS		
Resin (mold)	Ероху		
Lens color	Water Clear		
Dice	InGaN		
Emitted color	Pure Green		

Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.25mm (0.01") unless otherwised noted.
- 3. Specifications are subject to change without notice.

Part Number Chip Material		Color of Emission	Lens Type	Viewing Angle		
CS126AGT2C-R	InGaN	Green	Water Clear	140°		





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit		
Forward Current	lF	30	mA		
Reverse Current @ 5V	lR	10	μΑ		
Power Dissipation	Pd	111	mW		
Operating Temperature Range	Тор	-40~+85	°C		
Storage Temperature Range	Тѕтс	-40~+85	°C		
Peak Pulsing Current (1/8 duty f = 1KHz)	IFP	125	mA		
Soldering Temperature	TsoL	Max 260°C for	5 sec Max		

OPTICAL-ELECTRICAL CHARACTERISTICS

 $(TA=25^{\circ}C)$

Parameter	Symbol	Test Condition	Value			l lait
वावागादादा			Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 20mA	320	510	-	mcd
Forward Voltage	VF	IF = 20mA	1	3.2	3.7	V
Reverse Leakage Current	lR	VR = 5V	-	-	10	μΑ
Viewing Angle at 50% Iv	201/2	IF = 20mA	ı	140	-	Deg
Peak Wavelength	λР	IF = 20mA	-	520	-	nm
Dominant Wavelength	λD	IF = 20mA	520	525	530	nm

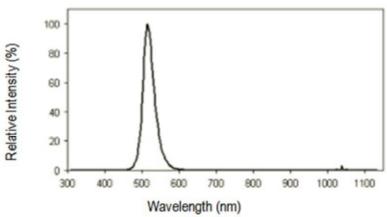
^{*}Tolerance of viewing angle: -10 / +5 deg.



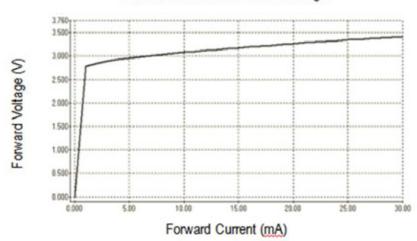


OPTICAL CHARACTERISTIC CURVES

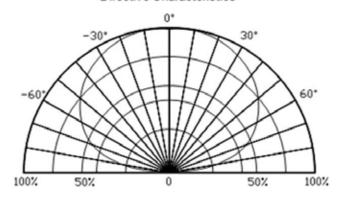
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage



Directive Characteristics

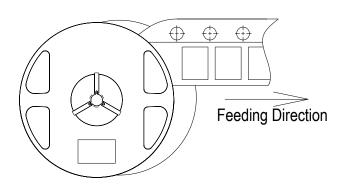




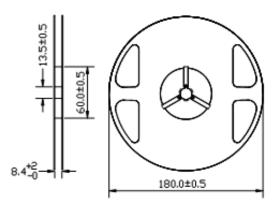


PACKAGING SPECIFICATION

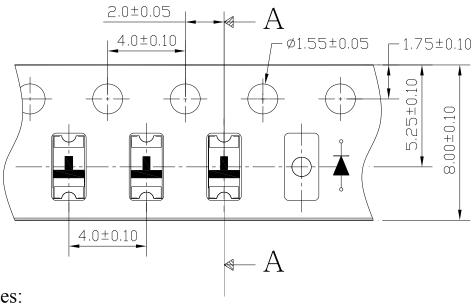
• Feeding Direction

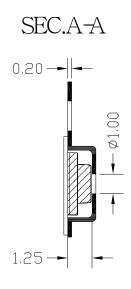


• Dimensions of Reel (Unit: mm)



• Dimensions of Tape (Unit: mm)





Notes:

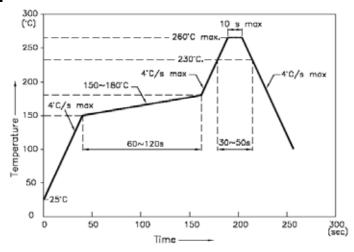
- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- 3. The cathode is oriented towards the tape sprocket hole.
- 4. 3,000pcs/Reel





SOLDERING CONDITIONS

REFLOW PROFILE



NOTES:

- 1. We recommend the reflow temperature 245°C (±5°C).the maximum soldering temperature should be limited to 260°C.
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.
 - Soldering iron
 - Basic spec is \leq 5sec when 260°C. If temperature is higher, time should be shorter
 - (+10°C \rightarrow -1sec). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

Rework

- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron cannot touch copper foil.
- 3. Twin-head type is preferred.

